Compliant with IEC 62474/ D9.00

Semiconductor (Pevice Type: To / ZB / BX	NICROCHIP Somioandustor Davisa Tun	(A2V) 002 TO 02 Matter Tip	Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				JEDEC 97 Product Marking and/or Pkg. Labeling e3	
Basic Substance	Semiconductor Device Typ	e: IU/ZB/BA									es
Epox Renin No Lorente No Salentinory Incode    Trust Species   Most Compound   \$4.477   \$6.989   \$5.772   Physicis Renin No. 1 (1975)   \$6.987   \$6.972   \$7.722	Basic Substance	CAS Number			mg/part	ppm	114.11	(mg) Total	Mold Compound	% ot Total Weight	56.77
Priestic Resin (No. Br. Cr. S. 2002). No. destination Y models   Tracks Special   Model Compound   3.477   8.889   34.772	Silica, vitreous	60676-86-0	Mold Compound	48.255	96.992	482,545		Silica, vitreous	60676-86-0	85.00	
Epony Created Nevrolate   20000-95-22   Model Compound   1,391   2,786   1,300   2,700   1,000   2,000   1,0	Epoxy Resin (No bromine, No diantimony trioxide)	Trade Secret	Mold Compound	3.477	6.989	34,772		Epoxy Resin	Trade Secret	6.13	
Carton Block	Phenolic Resin (No Br / CL SbO3, No diantimony trioxide)	Trade Secret	Mold Compound					Phenolic Resin	Trade Secret	6.13	
Copper											
No.								Carbon Black		0.00	
Sherr									Total	100.00	•
Zinc	Iron	7439-89-6	Lead Frame	0.935		9,353	80.00	(mg) Total	Lead Frame	% of Total Weight	39.8
Protective Tubes of International Substances of the date of this document, there is no oregible reason to believe that the unavoidable impurity concentration of the chamical substances, if any, is believe the formation in this form concerning substances restricted by RoNS in Microchip Technology incorporated as series from the best of the store, believe that from the substances of the region generatory of tasks in this in the specific product in shipsed and the substances of the region generatory of tasks in this in the specific product in shipsed and the substances of the region generatory of tasks in this in the specific product in shipsed and the substances of the region of o	Silver	7440-22-4	Lead Frame	0.758	1.524	7,582		Copper	7440-50-8	95.54	
Silver   1440-22-4   Die Attach   0.066   0.134   664   Exox (Parish   1.000   Parish   1.0			Lead Frame								
Egypory Resiri 9033-36-5   De Attach   0,017   0,034   1692	Phosphorous	7723-14-0	Lead Frame	0.033	0.066	328		Silver	7440-22-4	1.91	
Plantic Particular 1900 (1900)	Silver	7440-22-4	Die Attach	0.066	0.134	664		Zinc	7440-66-6	0.13	
Phenoic faradrener 92-88-6 Die Allach 0.000 0.001 3 0.8 (mg) Total Die Allach 15-009  Buth cellisorieve accidate 112-07-2 Die Allach 0.001 0.001 7 0.001 7 0.001 12-000 1 0.001 12-000 1 0.001 12-000 1 0.001 12-000 1 0.001 12-000 1 0.000 1 0.001 12-000 1 0.000 1 0	Epoxy Resin	9003-36-5	Die Attach	0.017	0.034	169		Phosphorous	7723-14-0	0.08	
Butyl cellosolve acetate 112-07-2 Die Attach 0.001 0.001 7.000 0.0	t-Butyl phenyl glycidyl ether	3101-60-8	Die Attach	0.006	0.011	57			Total	100.00	-
Silicon 7440-21-3 Chip (Die) 0.800 1.808 8.000 1.000 1.808 1.000 1	Phenolic hardener	92-88-6	Die Attach	0.000	0.001	3	0.18	(mg) Total	Die Attach	% of Total Weight	0.09
Silicon 7440-21-3 Chip (Die) 0.800 1.508 8.000 1											
Gold 7440-57-5 Burg or external states from 1 7440-51-5 Purp or external states (pox). Mater 1st 7440-51-5 Purp or external states (pox). Purp or ext											
Tin 7440-31-5 Plating on external leads (press) - Matter Tin / International and 150°C let 1 tool 2.500 1.000 201.000 1.000.000 1.000.000 1.000.000 1.000.000											
Semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/663/EU (31 March 1.5.) and 2002/55/EC (Et-dr-U-Life Vehicles (ELV) without exemption (zero) and 200								t-Butyl phenyl glycidyl ether			
O.2010 g Total Mass semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/66/JEU (31 March ) and 2002/55/EC (End-of-Life Vehicles (ELV) without exemption (zero)  pliance with the above EU Directives has been verified via internal design controls, supplier declarations, and for analytical test data.  Inchmical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology reportated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is solely the threshold of regulatory concern for any regulatory scheme world-wide.  Ining compounds used by Microchip meet the UL94 V0 fiammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at //ul.com/globalleng/pages/offerings/industries/chemicals/plastics/  protective "Uses" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and sin "reels" may be made from PVC plastic.  Total  O.08 (mg) Total Wire Bond  Wire Bond  Vire Bond  Vi	Tin	7440-31-5									
semiconductor device and its homogenous materials comply with EU Directives: 200299EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/66/EU (31 March and 20029/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/66/EU (31 March and 20029/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/66/EU (31 March and 2015/66/EU (		•	TOTALS:	100.000	201.000	1,000,000		Butyl cellosolve acetate	112-07-2	0.80	
semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/663/EU (31 March of June 2011) and 2015/663/EU (31 Ma		0.2010	g Total Mass						Total	100.00	
ing compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at //ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ //ul.com/gl	mliance with the chave Ell Directives has been verified via in								Cnip (Die)	% of Total Weight	0.8
in "reels" may be made from PVC plastic.  Total 100.00  To	hemical substance is absent from the list above, the chemica	al substance is NOT an	n intentional ingredient in the semiconductor device and, to						7440-21-3	100	0.8
ochip Technology Incorporated believes the information in this form concerning substances restricted by ROHS in Microchip Technology Incorporated's semiconductor devices in original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the pleteness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier mation is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is indeed only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of antis, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.  The average weight of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of antis, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.  The average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of antis, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.  The average weight of the average weight of the average weight of the average weight of anticipated significant toxic metals contained within silicon devices (silicon IC) in the finished parts.  The average weight of anticipated significant toxic metals contained within silicon devices (silicon IC) in the finished parts and the average weight of anticipated significant toxic metals contained within silic	hemical substance is absent from the list above, the chemica rporated's knowledge and belief as of the date of this docume below the threshold of regulatory concern for any regulatory sling compounds used by Microchip meet the UL94 V0 flamma //ul.com/global/eng/pages/offerings/industries/chemicals/plas	al substance is NOT an ent, there is no credible scheme world-wide. ability standard for plas stics/	n intentional ingredient in the semiconductor device and, to e reason to believe that the unavoidable impurity concentr stics. You can access the UL iQTM family of databases to d	ation of the cho	emical substa	nce, if any, is	0.08	Doped Silicon	7440-21-3 Total	100	
ranties provided by Microchip Technology Incorporated does not provide any warranty, express of implied, with respect to the information provided in this declaration. The excussive, immed product any warranty, express of implied, with respect to the information provided in this declaration. The excussive, limited product any warranty, express of implied, with respect to the information provided in this declaration. The excussive, limited product and the excussive, limited products and the excussive products.	hemical substance is absent from the list above, the chemica rporated's knowledge and belief as of the date of this docume below the threshold of regulatory concern for any regulatory sling compounds used by Microchip meet the UL94 V0 flamma //ul.com/global/eng/pages/offerings/industries/chemicals/plas protective "tubes" in which the specific product is shipped ar	al substance is NOT an ent, there is no credible scheme world-wide. ability standard for plas stics/	n intentional ingredient in the semiconductor device and, to e reason to believe that the unavoidable impurity concentr stics. You can access the UL iQTM family of databases to d	ation of the cho	emical substa	nce, if any, is	0.08	Doped Silicon  (mg) Total	7440-21-3 Total Wire Bond 7440-57-5	100 100.00 % of Total Weight	
rered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or of this tificate of Compliance for semiconductor products.  Tin 7440-31-5 100.00  Total 100.00	hemical substance is absent from the list above, the chemical reporated's knowledge and belief as of the date of this docume below the threshold of regulatory concern for any regulatory siling compounds used by Microchip meet the UL94 V0 flamma //ul.com/global/eng/pages/offerings/industries/chemicals/plat protective "tubes" in which the specific product is shipped are in "reels" may be made from PVC plastic.  Ochip Technology Incorporated believes the information in the original packing materials is true and correct to the best of it pleteness and accuracy of data in this form because it has be mation is often protected from disclosure as trade secrets an ided only as estimates of the average weight of these parts a	al substance is NOT an ent, there is no credible scheme world-wide. ability standard for plas stics/ re made from polyviny nis form concerning su ts knowledge and belie een compiled based on and some information m and the average weight	n intentional ingredient in the semiconductor device and, to a reason to believe that the unavoidable impurity concentricts. You can access the UL iQTM family of databases to or chloride (PVC) plastic. "Window envelopes" used to hold abstances restricted by RoHS in Microchip Technology Income, as of the date listed in this form. Microchip Technology in the ranges provided in Material Safety Data Sheets provided by subcontract assemblers and of anticipated significant toxic metals components. These	ation of the chi obtain a test rep the packing sl orporated's ser Incorporated ca ed by raw mated draw materials	emical substance ort at  ip on the oute niconductor d annot guarant erial suppliers.	r box and evices in ee the . Supplier rmation is	0.08	Doped Silicon  (mg) Total	7440-21-3 Total Wire Bond 7440-57-5	100 100.00 % of Total Weight	
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